

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1350isw#pbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.751152

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.006193 | 1000000 | 8244.66503906 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.184353 | 975000 | 245426.90625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.004538 | 24000 | 6041.38427734 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000057 | 300 | 75.8834152222 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000132 | 700 | 175.730010986 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.189080 | 1000000 | 251719.921875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.008359 | 1000000 | 11128.7148438 | | |
| | | External Plating Total: | | | | 0.008359 | 1000000 | 11128.7148438 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001513 | 1000000 | 2014.23864746 | | |
| Internal Plating Total: | | | | 0.001513 | 1000000 | 2014.23864746 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001548 | 750000 | 2060.83374023 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000516 | 250000 | 686.944519043 | | |
| Die Attach Total: | | | | 0.002064 | 1000000 | 2747.77807617 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.081459 | 150000 | 108445.382812 | | |
| | | Bromine (Br) | 40039-93-8 | 0.005431 | 10000 | 7230.22460938 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.439879 | 810000 | 585605.5625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.016292 | 30000 | 21689.3417969 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.543061 | 1000000 | 722970.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000882 | 1000000 | 1174.19592285 | | |
| | | | | | TOTAL MASS (g) : | 0.751152 | | |